

# 10.1 inch E-paper Display Series

**GDEW101C01** 

Dalian Good Display Co., Ltd.





# **Product Specifications**



Customer	Standard		
Description	10.1" E-PAPER DISPLAY		
Model Name	GDEW101C01		
Date	2020/11/30		
Revision	1.1		

Design Engineering		
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# **Revision History**

Rev.	<b>Issued Date</b>	Revised Contents
1.1	Nov.30.2020	Preliminary



### **1.Over View**

The display is a TFT active matrix electrophoretic display, with interface and a reference system design. The 10.1" active area contains  $1680 \times 2232$  pixels, and has 2-16 gray levels (1-4 bits) white/black full display capabilities. With color filter, it also supports a full color model with 4096 colors display.

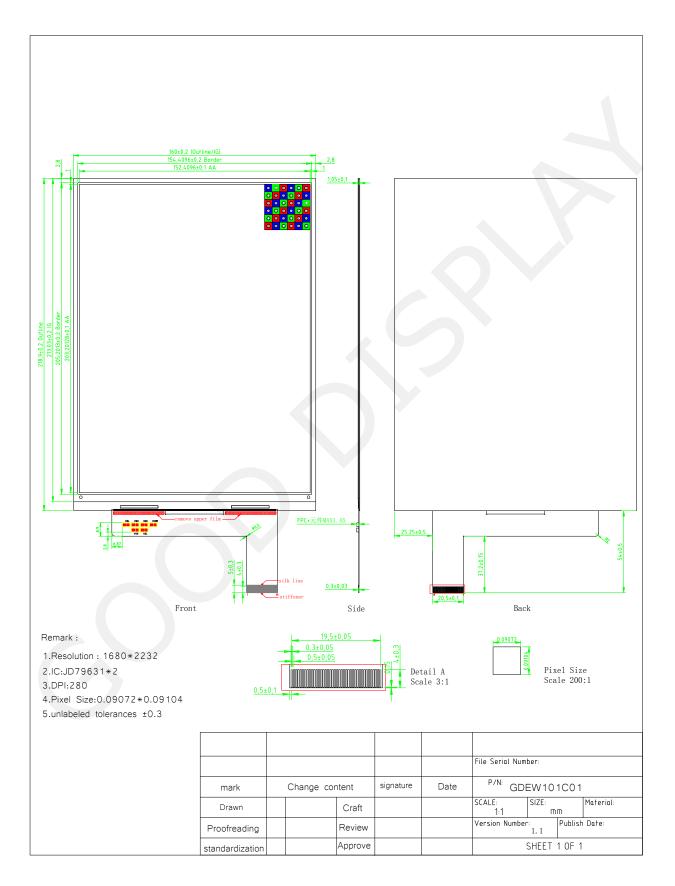
### 2.Features

- Carta high contrast reflective/electrophoretic technology
- 1680×2232 resolution
- Ultra wide viewing angle
- Low power consumption
- Pure reflective mode
- Bi-stable
- Commercial temperature range
- Landscape, portrait mode

### 3. Mechanical Specifications

Parameter	Specifications	Unit	Remark
Screen Size	10.1	Inch	
Display Resolution	1680(H)×2232 (V)	Pixel	Dpi: 280
Active Area	152.4096(H)×203.2013(V)	mm	
Pixel Pitch	0.09072×0.09104	mm	
Pixel Configuration	Square		
<b>Outline Dimension</b>	160(H)×218.9 (V) ×1.05(D)	mm	
Weight	TBD	g	

### 4. Mechanical Drawing of DES module



# 6. Input/Output Terminals

# 6-1. Pin out List

Pin #	Single	Description		
1	VGL	Negative power supply gate driver		
2	NC	No connection		
3	VGH	Positive power supply gate driver		
4	NC	No connection		
5	VDD	Digital power supply drivers		
6	Mode	Output mode selection gate driver		
7	CKV	Clock gate driver		
8	SPV	Start pulse gate driver		
9	VSS	Ground		
10	VCOM	Common connection		
11	VDD	Digital power supply drivers		
12	VSS	Ground		
13	XCL	Clock source driver		
14	D0	Data signal source driver		
15	D1	Data signal source driver		
16	D2	Data signal source driver		
17	D3	Data signal source driver		
18	D4	Data signal source driver		
19	D5	Data signal source driver		
20	D6	Data signal source driver		
21	D7	Data signal source driver		
22	VSS	Ground		
23	D8	Data signal source driver		
24	D9	Data signal source driver		
25	D10	Data signal source driver		
26	D11	Data signal source driver		
27	D12	Data signal source driver		
28	D13	Data signal source driver		
29	D14	Data signal source driver		
30	D15	Data signal source driver		
31	XSTL	Start pulse gate driver		
32	XLE	Latch enable source driver		
33	XOE	Output enable source driver		
34	TEST	Internal test pin (Note 1)		
35	NC	No connection		
36	VPOS	Positive power supply source driver		
37	NC	No connection		

38	VNEG	Negative power supply source driver		
39	NC	No connection		
40	Border	Border connection		

**Note 1:** Please connect to VDD voltage.

# **7. Electrical Characteristics**

# 7-1.Absolute maximum rating

Parameter	Symbol	Rating	Unit
Logic Supply Voltage	VDD	-0.3 to +5	V
Positive Supply Voltage	V <sub>POS</sub>	-0.3 to +18	V
Negative Supply Voltage	V <sub>NEG</sub>	-0.3 to -18	V
Max .Drive Voltage Range	$V_{POS}$ - $V_{NEG}$	36	V
Supply Voltage	VGG	-0.3 to +45	V
Supply Voltage	VEE	-25.0 to +0.3	V
Supply Range	VGG-VEE	-0.3 to +45	V
Operating Temp. range	T <sub>OPR</sub>	-20 to +60	°C
Storage Temp. range	T <sub>STG</sub>	-25 to +70	°C

# 7-2.Panel DC Characteristics

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Single ground	V <sub>SS</sub>		-	0	-	V
Lagia Sumply Valtage	V <sub>DD</sub>		1.7	3.0	3.6	V
Logic Supply Voltage	I <sub>VDD</sub>	$V_{DD}=3.0V$	-	3.1	7.8	mA
Cata Magatina Sumplu	VGL		-20	-	VNEG-4	V
Gate Negative Supply	I <sub>GL</sub>	VGL=-20V	-	1.2	12	mA
Cata Davitina Comula	VGH		7	VGL+42	VGL+45	V
Gate Positive Supply	I <sub>GH</sub>	VGH=22V	-	1.2	2.5	mA
Source Negative Superly	V <sub>NEG</sub>	~	-15.4	-	-10	V
Source Negative Supply	I <sub>NEG</sub>	$V_{\rm NEG} = -15V$	-	8.5	160	mA
Source Desitive Superly	V <sub>POS</sub>		10	-	15	V
Source Positive Supply	I <sub>POS</sub>	$V_{POS} = 15V$	-	8.2	166	mA
Border Supply	V <sub>com</sub>		-4	Adjusted	-0.2	V
Asymmetry Source	V <sub>ASYM</sub>	$V_{POS} + V_{NEG}$	-800	0	800	mV
Common voltage	V <sub>COM</sub>		-4	Adjusted	-0.2	V
	I <sub>COM</sub>		-	0.2	-	mA
Panel Power	Р		-	285	4680	mW
Standby power panel	P <sub>STBY</sub>		-	-	1.3	mW

#### - Note 1:

- The maximum power consumption is measured using 85 Hz waveform with following pattern transition: from pattern of repeated 1 consecutive black scan lines followed by 1 consecutive white scan line to that of repeated 1 consecutive white scan lines followed by 1 consecutive black scan lines.

#### - Note 2:

- The Typical power consumption is measured using 85 Hz waveform with following pattern transition: from horizontal 4 gray scale pattern to vertical 4 gray scale pattern.

- The standby power is the consumed power when the panel controller is in standby mode.

#### - Note 3:

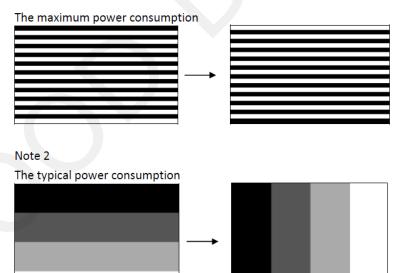
- The listed electrical/optical characteristics are only guaranteed under the controller & waveform provided by GOOD DISPLAY.

- Vcom is recommended to be set in the range of assigned value  $\pm$  0.1 V

- The maximum ICOM inrush current is about 1000 mA
- Customer need to use decoupling capacitors on each power rail at system board as below table to keep EPD driving power stable.

#### Note 4:

The maximum power consumption



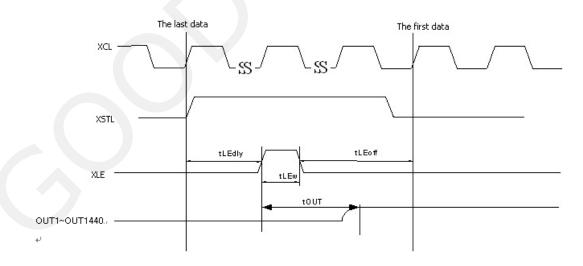
#### Note 5:

The decoupling capacitors on each power rail at customer system side

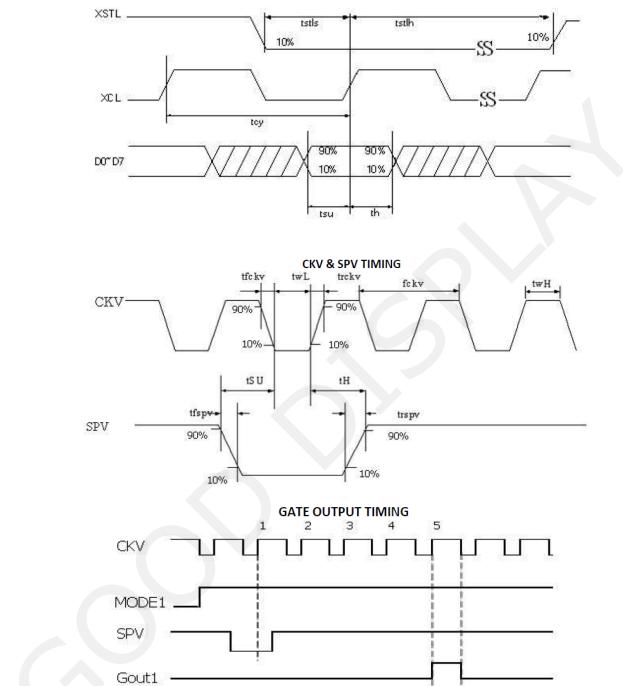
Power rail	Capacitors suggested ( uF / Tolerance)
IPOS	4.7uF x 2pcs / $\pm 10\%$
INEG	4.7uF x 2pcs / $\pm 10\%$
IGH	4.7uF x 1pcs / $\pm 10\%$
IGL	4.7uF x 1pcs / $\pm 10\%$
IDD	$4.7 \text{uF x 1pcs} / \pm 10\%$

### 7-3.Panel AC Characteristics VDD=3.0V, unless otherwise specified.

Parameter	Symbol	Min.	Тур.	Max.	unit
Clock frequency	fckv	-	-	200	kHz
Minimum "L" clock pulse width	twL	1	-	-	us
Minimum "H" clock pulse width	twH	1	I	-	us
Clock rise time	trckv	-	-	100	ns
Clock fall time	tfckv	-	-	100	ns
SPV setup time	tSU	100	I	twH-100	ns
SPV hold time	tH	100	I	twH-100	ns
Pulse rise time	trspv	-	-	100	ns
Pulse fall time	tfspv	-	-	100	ns
Clock XCL cycle time	tcy	22.22	-	-	ns
D0D7setup time	tsu	11	-		ns
D0D7 hold time	th	11	-	-	ns
XSTL setup time	tstls	0.5*tcy	-	0.8*tcy	ns
XSTL hold time	tstlh	0.5*tcy		-	ns
XLE on delay time	tLEdly	4.5*tcy	-	-	ns
LEH high-level pulse width	H EW	400			
(When VDD=1.7V to 2.1V)	tLEW	400	-	-	ns
XLE off delay time	tLEoff	250	-	-	ns
Output setting time to +/-30mV (C load=200pF)	tout	-	-	20	us







#### **CLOCK & DATA TIMING**

Note 1: First gate line on timing . After 5 CKV, gate line be on.

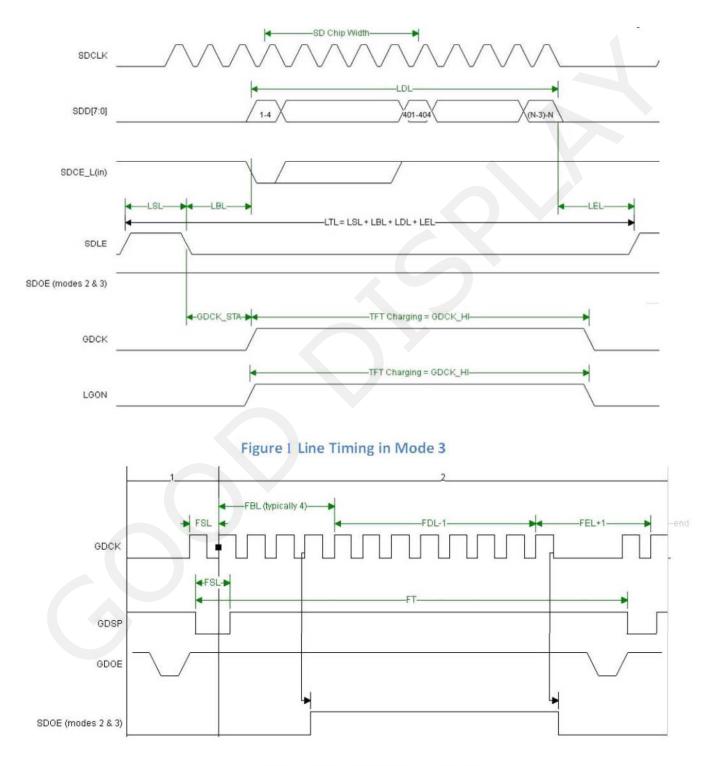
### 7-4. Refresh rate

The module applied at a maximum refresh rate of 85 Hz.

	Min	Max
Refresh rate	-	85Hz

### 7-5. Controller Timing

This timing mode is depicted on Figure 1 and Figure 2 and it refers to timing of Source Driver Output Enable (SDOE) and Gate Driver Clock (GDCK). Note, that in this mode LGON follows GDCK timing.





Mode	3					
SDCK(MHz)	44.61					
Pixel per SDCK	8					
Line Parameters	LSL	LBL	LDL	LEL	GDCK_STA	LGONL
(SDCK)	12	6	279	13	12	298
Line Parameters	-	-	-	-	-	-
(us)	0.27	0.13	6.25	0.29	0.27	6.68
Frame parameters	FSL	FBL	FDL	FEL	-	FR(Hz)
(lines)	4	6	1680	6	-	84.75
Frame parameters					-	-
(us)	27.8	41.7	11676	41.7	-	-

**Note 1 :** For parameters definition , see Section 6. Active Matrix Electronic Paper Display Timings

**Note 2 :** For Isis Controller GDCK\_STA and LGONL are not settable parameters ; GDCK\_STA=LBL, LGONL=LDL+0.5

**Note 3 :** For Freescale SoC GDOE Low pulse represent FSL and GDSP pulses with the first period of FBL

#### Note 4 :

SDCLK = XCL SDD[7:0] = D0~D7 SDCE\_L(in) = XSTL GDCK = CKV GDSP = SPV GDOE = Mode 1 SDOE = XOE

### **8.** Power on Sequence

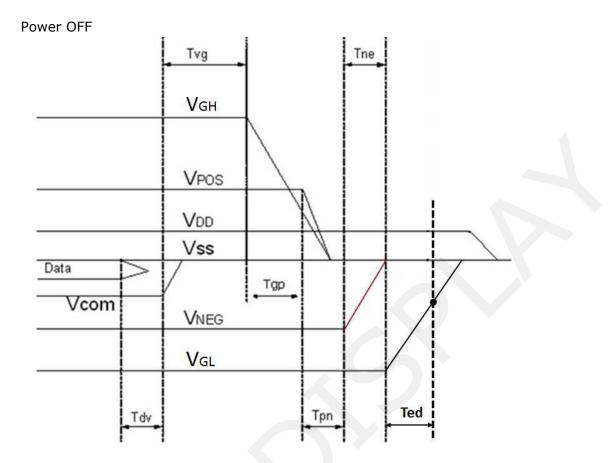
Power Rails must be sequenced in following order:

- 1. VSS $\rightarrow$ VDD $\rightarrow$ VNEG $\rightarrow$ VPOS (Source driver)  $\rightarrow$ VCOM
- 2. VSS $\rightarrow$ VDD $\rightarrow$ VGL $\rightarrow$ VGH(Gate drive)

POWER ON Tng Ten Tgv VGH VPOS VDD VSS Data VCOM VNEG VGL Tvd Tsd Tde Тер Тру ÷ Min Max

Tsd	30us	-
Tde	100us	-
Тер	1000us	-
Tpv	100us	-
Tvd	100us	-
Ten	Ous	-
Tng	1000us	-
Tgv	100us	-





	Min	Max	Remark
Tdv	100us	-	-
Tvg	Ous	-	-
Tgp	Ous	-	-
Tpn	Ous	-	-
Tne	Ous	-	-
Ted	0.5s	-	Discharged point @ -7.4 Volt

**Note 1:** Supply voltages decay through pull-down resistors.

**Note 2:** Turn off VGL power after VNEG and VPOS power discharged to GND state.

**Note 3:** VGL must remain negative of Vcom during decay period.

T-25℃

### 9. Optical characteristics

### 9-1. Specifications

Measurements are made with that the illumination is under an angle of 45 degrees, the detection is perpendicular unless otherwise specified.

						1	250
SYMBOL	PARAMETER	CONDITIONS	MIN	ТҮРЕ	MAX	UNIT	Note
R	Reflectance	White	20	25	-	%	Note 8-1
Gn	Nth Grey Level	-	-	$DS+(WS-DS) \times n/(m-1)$	-	L*	-
CR	Contrast Ratio	indoor	8		1	-	-
T <sub>update</sub>	Update time	25℃	-	1	-	Sec	-
Panel's life		-20°C~60°C		1000000 times or 5 years	-	-	Note 8-2

WS : White state; DS : Dark state, Gray state from Dark to White :

DS、G1、G2...、Gn...、Gm-2、WS m: 4、8、16 when 2、3、4 bit mode.

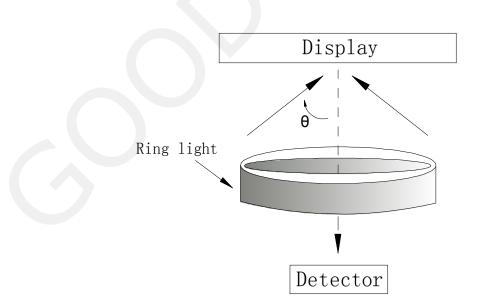
**Note 8-1:** Luminance meter: Eye – One Pro Spectrophotometer

Note 8-2: Each update interval time should be minimum at 180 seconds.

Note 8-3: When work in temperature 60 degree, suggest update once every 1hours.

### 9-2. Definition of contrast ratio

The contrast ratio (CR) is the ratio between the reflectance in a full white area (R1) and the reflectance in a dark area (Rd)() : R1: white reflectance Rd: dark reflectance CR = R1/Rd

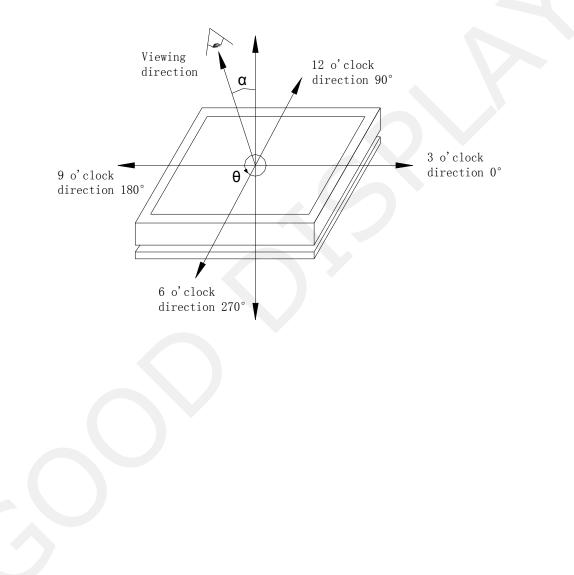


### 9-3. Reflection Ratio

The reflection ratio is expressed as :

 $R = Reflectance Factor white board \times (L center / L white board)$ 

L center is the luminance measured at center in a white area (R=G=B=1). L white board is the luminance of a standard white board. Both are measured with equivalent illumination source. The viewing angle shall be no more than 2 degrees.



### **10.** Handling, Safety and Environmental Requirements

#### Warning

The display glass may break when it is dropped or bumped on a hard surface. Handle with care.

Should the display break, do not touch the electrophoretic material. In case of contact with electrophoretic material, wash with water and soap.

#### Caution

The display module should not be exposed to harmful gases, such as acid and alkali gases, which corrode electronic components.

Disassembling the display module can cause permanent damage and invalidate the warranty agreements.

Observe general precautions that are common to handling delicate electronic components. The glass can break and front surfaces can easily be damaged. Moreover the display is sensitive to static electricity and other rough environmental conditions.

#### Data sheet status

Product specification | The data sheet contains final product specifications.

#### Limiting values

Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134).

Stress above one or more of the limiting values may cause permanent damage to the device.

These are stress ratings only and operation of the device at these or any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

#### Application information

Where application information is given, it is advisory and dose not form part of the specification.

#### Product environmental certification

RoHS

# 11. Reliability test

	TEST	CONDITION	METHOD	REMARK
1	High-Temperatu re Operation	T = 60°C, RH=20% for 240 hrs	When the experimental cycle finished, the DES samples will be taken out from the high temperature environmental chamber and set aside for a few minutes. As DESs return to room temperature, testers will observe the appearance, and test electrical and optical performance based on standard # IEC 60 068-2-2Bp.	When experiment finished, the DES must meet electrical and optical performance standards.
2	Low-Temperatu re Operation	T = -20°C for 240 hrs	When the experimental cycle finished, the DES samples will be taken out from the low temperature environmental chamber and set aside for a few minutes. As DESs return room temperature, testers will observe the appearance, and test electrical and optical performance based on standard # IEC 60 068-2-2Ab.	When experiment finished, the DES must meet electrical and optical performance standards.
3	High-Temperatu re Storage	T = +70°C, RH=20% for 240 hrs Test in white pattern	When the experimental cycle finished, the DES samples will be taken out from the high temperature environmental chamber and set aside for a few minutes. As DESs return to room temperature, testers will observe the appearance, and test electrical and optical performance based on standard # IEC 60 068-2-2Bp.	When experiment finished, the DES must meet electrical and optical performance standards.
4	Low-Temperatu re Storage	T = -25°C for 240 hrs Test in white pattern	When the experimental cycle finished, the DES samples will be taken out from the low temperature environmental chamber and set aside for a few minutes. As DESs return to room temperature, testers will observe the appearance, and test electrical and optical performance based on standard # IEC 60 068-2-2Ab	When experiment finished, the DES must meet electrical and optical performance standards.
5	High Temperature, High- Humidity Operation	T=+40°C, RH=90% for240hrs	When the experimental cycle finished, the DES samples will be taken out from the environmental chamber and set aside for a few minutes. As DESs return to room temperature, testers will observe the appearance, and test electrical and optical performance based on standard # IEC 60 068-2-3CA.	When experiment finished, the DES must meet electrical and optical performance standards.
6	High Temperature, High- Humidity Storage	T=+60°C, RH=80% for 240 hrs Test in white pattern	When the experimental cycle finished, the DES samples will be taken out from the environmental chamber and set aside for a few minutes. As DESs return to room temperature, testers will observe the appearance, and test electrical and optical performance based on standard # IEC 60 068-2-3CA.	When experiment finished, the DES must meet electrical performance standards.
7	Temperature Cycle	[-25°C 30mins]→ [+70°C, RH=20% 30mins],	<ol> <li>Samples are put in the Temp &amp; Humid. Environmental Chamber. Temperature cycle starts with -25°C, storage period 30 minutes. After 30 minutes, it needs 30min to</li> </ol>	When experiment finished, the DES must meet electrical

		70cycles,	let temperature rise to 70°C. After 30min, temperature	and optical
		Test in white	will be adjusted to $70^{\circ}$ C, RH=20% and storage period	performance
		pattern	is 30 minutes. After 30 minutes, it needs 30min to let	standards.
			temperature rise to -25 °C. One temperature cycle	
			(2hrs) is complete.	
			2. Temperature cycle repeats 70 times.	
			3. When 70 cycles finished, the samples will be taken out	
			from experiment chamber and set aside a few minutes.	
			As DESs return to room temperature, tests will	
			observe the appearance, and test electrical and optical	
			performance based on standard # IEC 60 068-2-14NB.	
8	UV exposure	560 W/m <sup>2</sup> for 168	Standard # IEC 60 068-2-5 Sa	
0	Resistance	hrs,35°C	Standard # IEC 00 006-2-5 Sa	
	Electrostatic	Machine model:		
9	discharge	+/-250V,	Standard # IEC61000-4-2	
		0Ω,200pF		
		1.04G,Frequency :		
	Package	10~500Hz		
10	Vibration	Direction : X,Y,Z	Full packed for shipment	
		Duration: 1 hours		
		in each direction		
		Drop from height		
		of 122 cm on		
	Package Drop Impact	Concrete surface		
11		Drop sequence:1	Full packed for shipment	
11		corner, 3edges,	run packed for sinpilient	
		6face		
		One drop for		
		each.		

Actual EMC level to be measured on customer application.

#### Note:

(1) The protective film must be removed before temperature test.

(2) In order to make sure the display module can provide the best display quality, the update should be made after putting the display module in stable temperature environment for 4 hours at 25 C.

### 12. Point and line standard

#### **Shipment Inseption Standard**

Part-A: Active area Part-B: Border area

Equipment: Electrical test fixture, Point gauge Outline

#### dimension: 160(H)×218.9 (V) ×1.05(D)mm

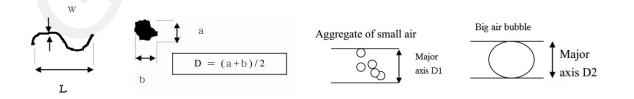
	Temperature	Humidity	Illuminan	ice Distance	Time	Angle	
Environment	23±2°C	55± 5%RH	1200~ 1500Lu	300 mm	35 Sec		
Name	Causes	Spot size		Part-A	Part-B		
	D/W motin close on		$D \leq 0$	.25mm	Ignore		
Spot	B/W spot in glass or	0.	25mm $< I$	4	Ignore		
Spot	protection sheet, foreign mat. Pin hole	0	.4mm < D	2			
	Ioreign mat. Fin noie		0.5mm	0			
	Scratch on glass or	Leng	gth	Width	Part-A		
Scratch or line defect	Scratch on FPL or	L ≤3mm		W≤0.1 mm	Ignore	e	
Scratch of the defect	Particle is Protection	3 mm < L	≤ 6mm	0.1 mm <w≤ 0.2mm<="" td=""><td>2</td><td>Ignore</td></w≤>	2	Ignore	
	sheet.	6 mm	< L	0.2mm < W	0		
		D1, D2 $\leq 0.3 \text{ mm}$			Ignore		
Air bubble	Air bubble	0.3	8 mm < D1,D	4	Ignore		
		0.5mm < D1, D2			0		
Side Fragment			x y Ty	$\overline{\langle}$			
	X $\leqslant$ 6mm, Y $\leqslant$ 1mm & display is ok, Ignore						

Remarks: Spot define: That only can be seen under WS or DS defects.

Any defect which is visible under gray pattern or transition process but invisible under black and white is disregarded. Here is definition of the "Spot" and "Scratch or line defect". Spot: W > 1/4L Scratch or line defect:  $W \le 1/4L$ 

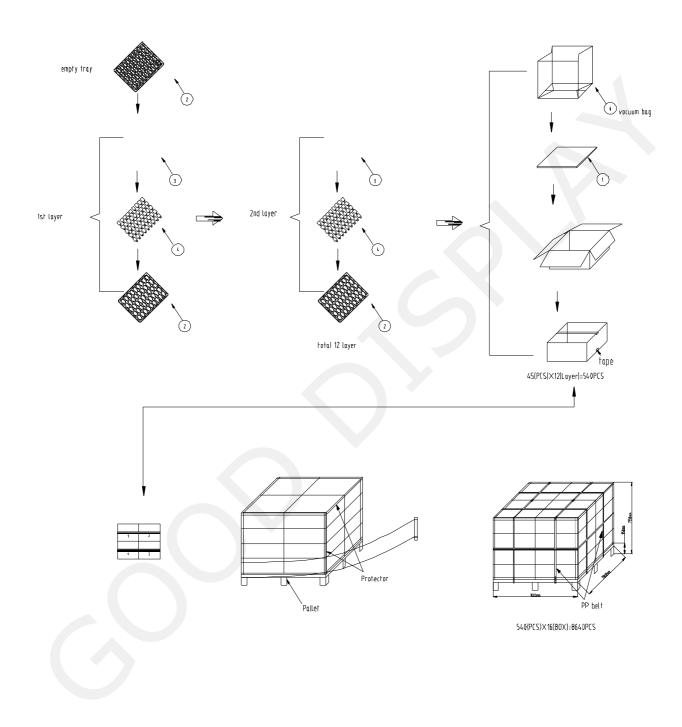
Definition for L/W and D (major axis)

FPC bonding area pad doesn't allowed visual inspection.





# 13. Packing



### 14. Precautions

- (1) Do not apply pressure to the EPD panel in order to prevent damaging it.
- (2) Do not connect or disconnect the interface connector while the EPD panel is in operation.
- (3) Do not touch IC bonding area. It may scratch TFT lead or damage IC function.
- (4) Please be mindful of moisture to avoid its penetration into the EPD panel, which may cause damage during operation.
- (5) If the EPD Panel / Module is not refreshed every 24 hours, a phenomena known as "Ghosting" or "Image Sticking" may occur. It is recommended to refreshed the ESL /EPD Tag every 24 hours in use case. It is recommended that customer ships or stores the ESL / EPD Tag with a completely white image to avoid this issue
- (6) High temperature, high humidity, sunlight or fluorescent light may degrade the EPD panel's performance. Please do not expose the unprotected EPD panel to high temperature, high humidity, sunlight, or fluorescent for long periods of time.
- (7) For more precautions, please click on the link: https://www.good-display.com/news/80.html